162162

ABSTRACT

A semiconductor wafer is applied to a support disk via an intervening adhesive layer 10 with the front side of the semiconductor wafer facing the adhesive layer, which is sensitive to a certain exterior factor for reducing its adhesive force; the semiconductor wafer is ground on the rear side; the wafer-and-support combination is applied to a dicing adhesive tape with the so ground rear side facing the dicing adhesive tape, which is surrounded and supported by the circumference by a dicing frame; the certain exterior factor is effected on the intervening adhesive layer to reduce its adhesive force; and the intervening adhesive layer and support disk are removed from the semiconductor wafer or chips without the possibility of damaging the same.

G00002